

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage Peak Reverse Voltage	V_{RRM} V_{RWM} V_{RM}	60	V
RMS Reverse voltage	$V_{R(RMS)}$	42	V
Average Rectified Output Current	I_O	5	A
Non-Repetitive Peak Forward Surge Current	I_{FSM}	120	A
Junction Temperature Range	$T_{J\ MAX}$	125	°C
Storage Temperature Range	T_{stg}	-55 125	°C
Typical Thermal Resistance	$R_{\theta JA}$ Note 1	85	°C/W

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_{BR}	$I_R=1mA$	60			V
Forward voltage	V_F	$I_F=2A$ $T_J=25^{\circ}C$		0.39	0.45	V
		$I_F=2A$ $T_J=125^{\circ}C$		0.30		V
		$I_F=5A$ $T_J=25^{\circ}C$		0.47	0.55	V
		$I_F=5A$ $T_J=125^{\circ}C$		0.43		V
Instantaneous Reverse Current	I_R Note 1	$V_R=60V$ $T_J=25^{\circ}C$		100	500	uA
		$V_R=60V$ $T_J=100^{\circ}C$		10		mA
		$V_R=60V$ $T_J=125^{\circ}C$		40		mA

/Notes

1. FR-4 PCB 2

/FR-4 PCB, 2oz. Copper, minimum recommended pad

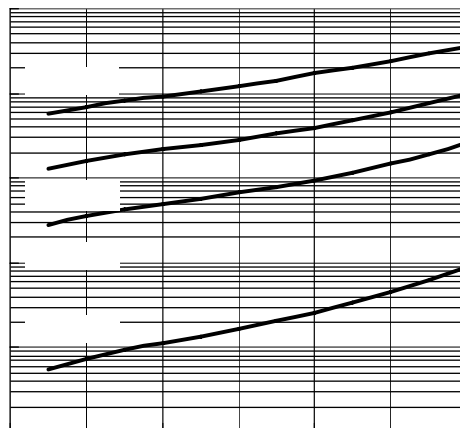
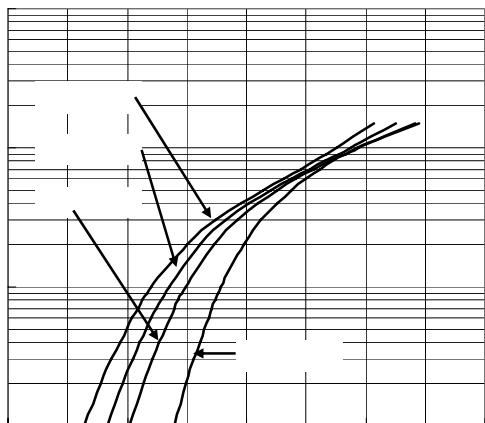
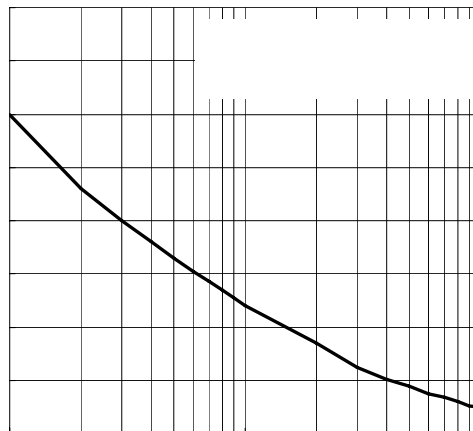
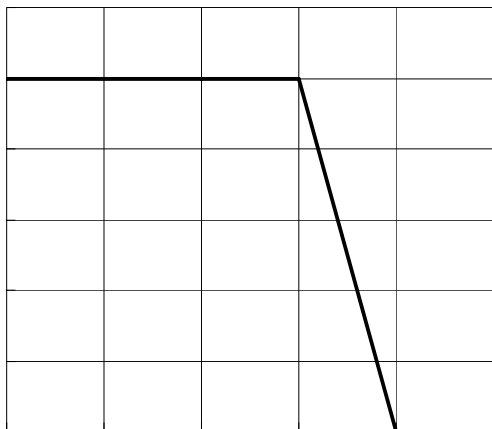
layout per.

2.

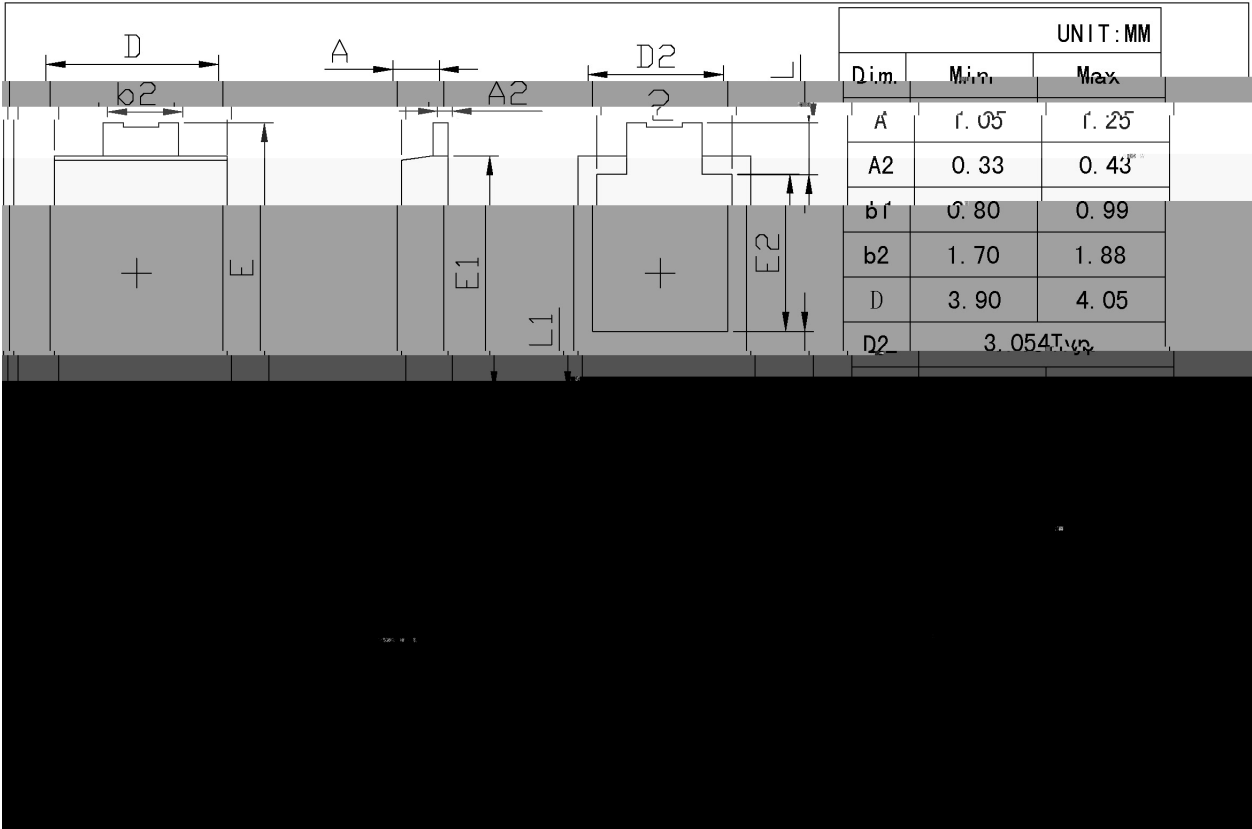
/Short duration pulse test used to minimize self-heating

effect.

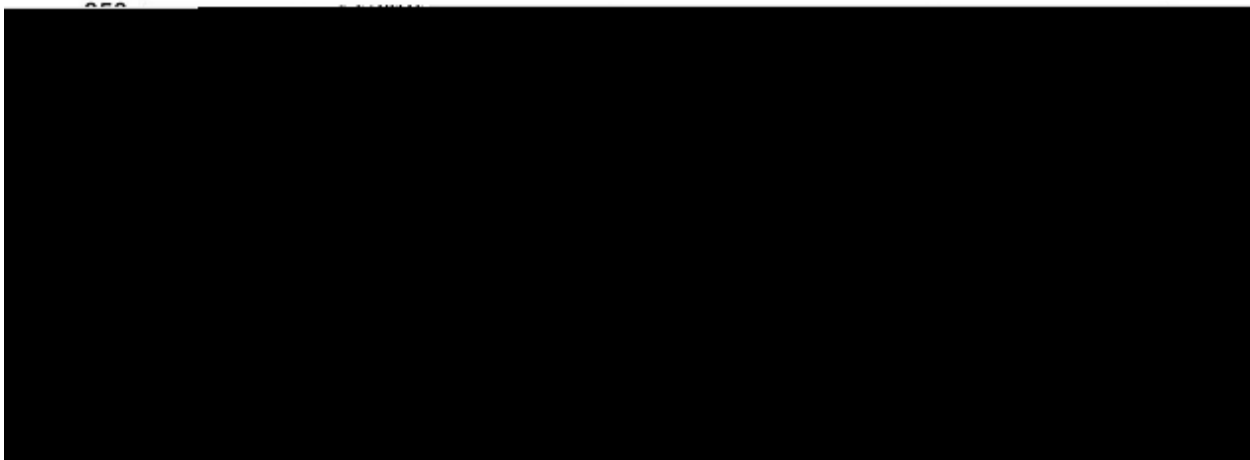
/ Electrical Characteristic Curve



/ Package Dimensions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | |
|---|---------|-----------|---|
| 1 | 150 180 | 60 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | 2 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ Notices